



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752 Distribute</b>	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	<b>Material Info Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>
<b>* : Required Field</b>			

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2014-07-31</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	<b>LAURENT TOSI</b>	<b>Representative Title</b>	<b>MMS MD CHAMPION</b>
<b>Representative Phone *</b>	33 442 685 795	<b>Representative Email *</b>	<a href="mailto:laurent.tosi@st.com">laurent.tosi@st.com</a>
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8S207S6T6CTR	U24Y*765XXXV	A	959	2014-07-31
Amount		UoM	Unit type	ST ECOPACK Grade
350.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	44	L bend	
Comment	LQFP 44 10x10x1.4 1.0			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	U24Y*765XXXV					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	6.698	mg	supplier	die	Silicon (Si)	7440-21-3		6.465	mg	965213	18471
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	2687	51
Die or Dies				supplier	metallization	Copper (Cu)	7440-50-8		0.060	mg	8958	171
Die or Dies				supplier	metallization	Tantalum (Ta)	7440-25-7		0.034	mg	5076	97
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	1344	26
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.016	mg	2389	46
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.096	mg	14333	274
Lead-frame	Other inorganic materials	77.156	mg	supplier	alloy	Copper (Cu)	7440-50-8		73.858	mg	957257	211022
Lead-frame				supplier	alloy	Nickel (Ni)	7440-02-0		2.303	mg	29852	6581
Lead-frame				supplier	alloy	Silicium (Si)	7440-21-3		0.499	mg	6468	1426
Lead-frame				supplier	alloy	Magnesium (Mg)	7439-95-4		0.115	mg	1493	329
Lead-frame				supplier	coating	Nickel (Ni)	7440-02-0		0.354	mg	4588	1011
Lead-frame				supplier	coating	Palladium (Pd)	7440-05-3		0.014	mg	186	41
Lead-frame				supplier	coating	Gold (Au)	7440-57-5		0.012	mg	157	35
Die Attach	Other inorganic materials	2.498	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		1.923	mg	770000	5495
Die Attach				supplier	glue or soft solder	Epoxy Cresol Novolak	29690-82-2		0.564	mg	226000	1613
Die Attach				supplier	glue or soft solder	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.010	mg	4000	29
Wires	Other inorganic materials	0.585	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.579	mg	990000	1654
Wires				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.006	mg	10000	17
Encapsulation	Other inorganic materials	263.060	mg	supplier	Moulding Compound	Silica, vitreous	60676-86-0		227.730	mg	865693	650656
Encapsulation				supplier	Moulding Compound	Epoxy resin	Proprietary		20.937	mg	79589	59819
Encapsulation				supplier	Moulding Compound	Phenol resin	Proprietary		13.085	mg	49743	37387
Encapsulation				supplier	Moulding Compound	Carbon black	1333-86-4		1.309	mg	4974	3739
Finishing	Other inorganic materials	0.004	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.004	mg	930510	10
Finishing				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	37710	0
Finishing				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	31780	0